

# SOLDER PASTES

## SOLDER PASTES – NO CLEAN LEAD FREE

PRODUCT	DESCRIPTION	ALLOY	% METAL LOADING	TACK, g/mm <sup>2</sup>	PRINT SPEED, mm/s	IPC/J-STD-004 CLASSIFICATION
<b>MULTICORE® LF318™</b>	A halide-free, no-clean, Pb-free solder paste that has excellent humidity resistance and a broad process window for both reflow and printing. Offers high tack to resist component movement during high-speed placement, long printer abandon times and excellent solderability over a wide range of reflow profiles in air and N2 reflow ovens and across a wide range of surface finishes including Ni/Au, immersion Sn, Immersion Ag and OSP Cu. Proflow compatible. Available with both AGS (20-45µm, equivalent to IPC type 3) and DAP (20-38µm, equivalent to IPC type 4) powder.	96SC (95.5Sn 3.8Ag 0.7Cu, SAC387, 217C) 97SC (96.5Sn 3.0Ag 0.5Cu, SAC305, 217C)	88.5 and 89.0	1.8 AGS (Type 3 powder) 2.3 DAP (Type 4 powder)	25 - 150	ROLO
<b>MULTICORE® LF620™</b>	Halide-free, no clean, low voiding, Pb-free solder paste with excellent humidity resistance and broad process window. Suitable for both reflow and printing.	96SC (95.5Sn 3.8Ag 0.7Cu, 217°C) 97SC (96.5Sn 3.0Ag 0.5Cu, 217°C)	88.5	2.3	25 - 150	ROLO
<b>MULTICORE® LF700™</b>	A halide-free, no clean, Pb-free solder paste with a broad process window for printing, reflow and humidity resistance.	96SC (SAC387) 97SC (SAC305)	88.5	2.4	70 - 150	ROLO

## SOLDER PASTES – NO CLEAN TIN-LEAD

<b>MULTICORE® MP218™</b>	High activity, soft residue, colorless, halide-free, no-clean solder paste that displays outstanding resistance to high temperature and humidity environments. Suitable for a large range of assembly processes, including rheo pump, proflow, large high-den.	Sn62/Sn63/63S4 (Anti-Tombstoning)	89.5 and 90	1.6	25 - 150	ROLO
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## SOLDER PASTES – WATER WASH

<b>MULTICORE® WS200™</b>	High performance, water-washable solder paste. Residues are readily removed with DI water, without the need for a saponifier. WS200™ has good open time with excellent print definition and soldering activity.	Sn62/Sn63/63S4 (Anti-Tombstoning)	88.5	0.8	25 - 100	ORH1
<b>MULTICORE® WS300™</b>	Flux system specially formulated for lead-free alloys. High performance, water washable solder paste. Residues are easily removed with DI water, without the need for a saponifier. Good open time with excellent print definition and soldering.	96SC (SAC387) 97SC (SAC305)	87	0.8	25 - 100	ORH1